FAIRCHILD
SEMICONDUCTOR™

GlobalOptoisolator™

VDE	UL	CSA	SETI	SEMKO	DEMKO	NEMKO	BABT

6-Pin DIP Optoisolators Transistor Output

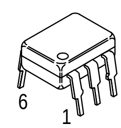
4N25
4N26
4N27
4N28

The 4N25, 4N26, 4N27 and 4N28 devices consist of a gallium arsenide infrared emitting diode optically coupled to a monolithic silicon phototransistor detector.

- Most Economical Optoisolator Choice for Medium Speed, Switching Applications
- Meets or Exceeds All JEDEC Registered Specifications
- ***To order devices that are tested and marked per VDE 0884 requirements, the suffix "V" must be included at end of part number. VDE 0884 is a test option.***

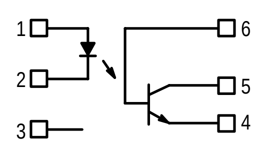
Applications

- General Purpose Switching Circuits
- Interfacing and coupling systems of different potentials and impedances
- I/O Interfacing
- Solid State Relays



STANDARD THRU HOLE

SCHEMATIC



PIN 1. LED ANODE
2. LED CATHODE
3. N.C.
4. EMITTER
5. COLLECTOR
6. BASE

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
INPUT LED			
Reverse Voltage	V_R	3	Volts
Forward Current — Continuous	I_F	60	mA
LED Power Dissipation @ T_A = 25°C with Negligible Power in Output Detector	P_D	120	mW
Derate above 25°C		1.41	mW/°C
OUTPUT TRANSISTOR			
Collector–Emitter Voltage	V_{CEO}	30	Volts
Emitter–Collector Voltage	V_{ECO}	7	Volts
Collector–Base Voltage	V_{CBO}	70	Volts
Collector Current — Continuous	I_C	150	mA
Detector Power Dissipation @ T_A = 25°C with Negligible Power in Input LED	P_D	150	mW
Derate above 25°C		1.76	mW/°C
TOTAL DEVICE			
Isolation Surge Voltage(1) (Peak ac Voltage, 60 Hz, 1 sec Duration)	V_{ISO}	7500	Vac(pk)
Total Device Power Dissipation @ T_A = 25°C	P_D	250	mW
Derate above 25°C		2.94	mW/°C
Ambient Operating Temperature Range	T_A	–55 to +100	°C
Storage Temperature Range	T_{stg}	–55 to +150	°C
Soldering Temperature (10 sec, 1/16″ from case)	T_L	260	°C

1. Isolation surge voltage is an internal device dielectric breakdown rating.
For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)[1]

Characteristic		Symbol	Min	Typ[1]	Max	Unit
INPUT LED						
Forward Voltage (I_F = 10 mA)	T_A = 25°C T_A = –55°C T_A = 100°C	V_F	— — —	1.15 1.3 1.05	1.5 — —	Volts
Reverse Leakage Current (V_R = 3 V)		I_R	—	—	100	µA
Capacitance (V = 0 V, f = 1 MHz)		C_J	—	18	—	pF
OUTPUT TRANSISTOR						
Collector–Emitter Dark Current (V_{CE} = 10 V, T_A = 25°C	4N25,26,27 4N28	I_{CEO}	— —	1 1	50 100	nA
(V_{CE} = 10 V, T_A = 100°C)	All Devices	I_{CEO}	—	1	—	µA
Collector–Base Dark Current (V_{CB} = 10 V)		I_{CBO}	—	0.2	—	nA
Collector–Emitter Breakdown Voltage (I_C = 1 mA)		$V_{(BR)CEO}$	30	45	—	Volts
Collector–Base Breakdown Voltage (I_C = 100 µA)		$V_{(BR)CBO}$	70	100	—	Volts
Emitter–Collector Breakdown Voltage (I_E = 100 µA)		$V_{(BR)ECO}$	7	7.8	—	Volts
DC Current Gain (I_C = 2 mA, V_{CE} = 5 V)		h_{FE}	—	500	—	—
Collector–Emitter Capacitance (f = 1 MHz, V_{CE} = 0)		C_{CE}	—	7	—	pF
Collector–Base Capacitance (f = 1 MHz, V_{CB} = 0)		C_{CB}	—	19	—	pF
Emitter–Base Capacitance (f = 1 MHz, V_{EB} = 0)		C_{EB}	—	9	—	pF
COUPLED						
Output Collector Current (I_F = 10 mA, V_{CE} = 10 V)	4N25,26 4N27,28	I_C (CTR)[2]	2 (20) 1 (10)	7 (70) 5 (50)	— —	mA (%)
Collector–Emitter Saturation Voltage (I_C = 2 mA, I_F = 50 mA)		$V_{CE(sat)}$	—	0.15	0.5	Volts
Turn–On Time (I_F = 10 mA, V_{CC} = 10 V, R_L = 100 Ω)[3]		t_{on}	—	2.8	—	µs
Turn–Off Time (I_F = 10 mA, V_{CC} = 10 V, R_L = 100 Ω)[3]		t_{off}	—	4.5	—	µs
Rise Time (I_F = 10 mA, V_{CC} = 10 V, R_L = 100 Ω)[3]		t_r	—	1.2	—	µs
Fall Time (I_F = 10 mA, V_{CC} = 10 V, R_L = 100 Ω)[3]		t_f	—	1.3	—	µs
Isolation Voltage (f = 60 Hz, t = 1 sec)[4]		V_{ISO}	7500	—	—	Vac(pk)
Isolation Resistance (V = 500 V)[4]		R_{ISO}	10^{11}	—	—	Ω
Isolation Capacitance (V = 0 V, f = 1 MHz)[4]		C_{ISO}	—	0.2	—	pF

1. Always design to the specified minimum/maximum electrical limits (where applicable).
2. Current Transfer Ratio (CTR) = I_C/I_F x 100%.
3. For test circuit setup and waveforms, refer to Figure 11.
4. For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

TYPICAL CHARACTERISTICS

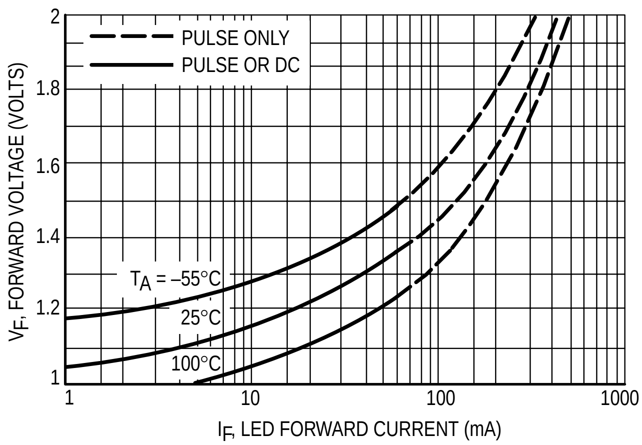


Figure 1. LED Forward Voltage versus Forward Current

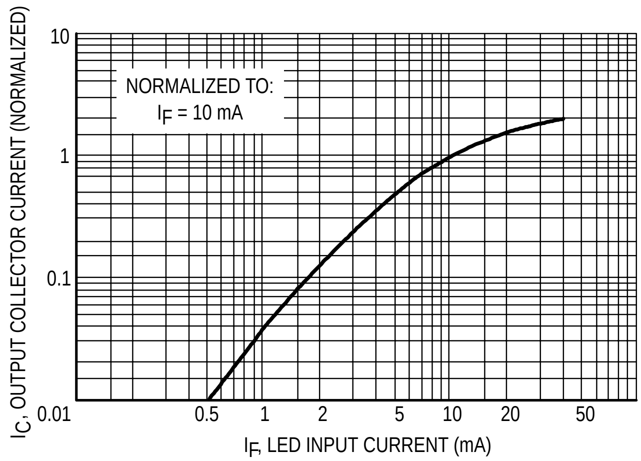


Figure 2. Output Current versus Input Current

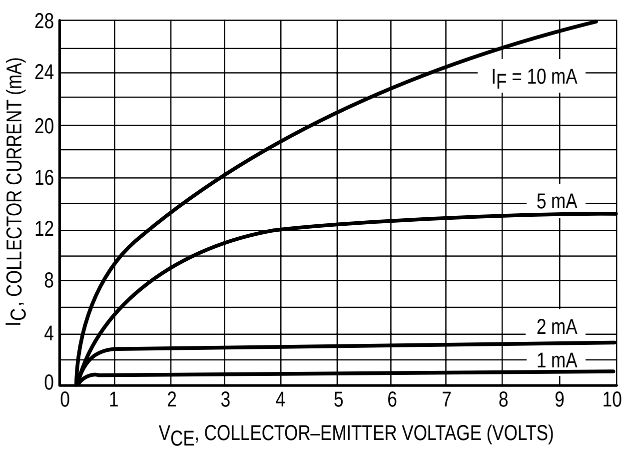


Figure 3. Collector Current versus Collector–Emitter Voltage

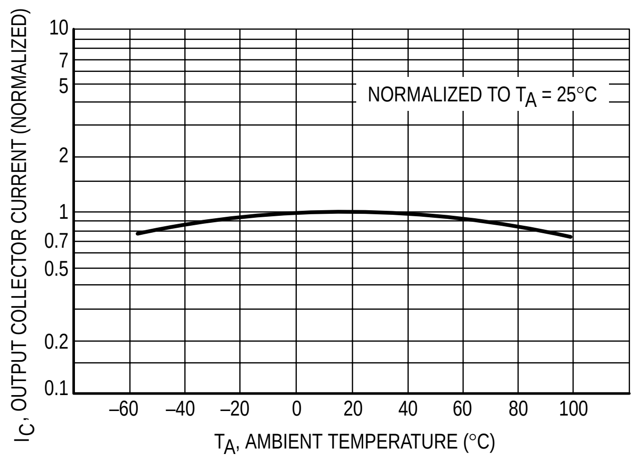


Figure 4. Output Current versus Ambient Temperature

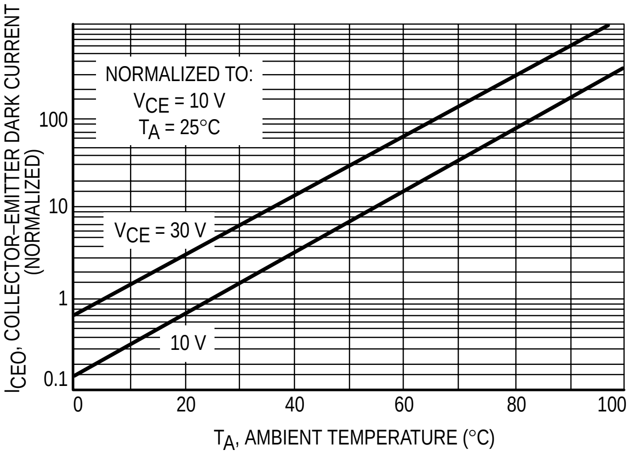


Figure 5. Dark Current versus Ambient Temperature

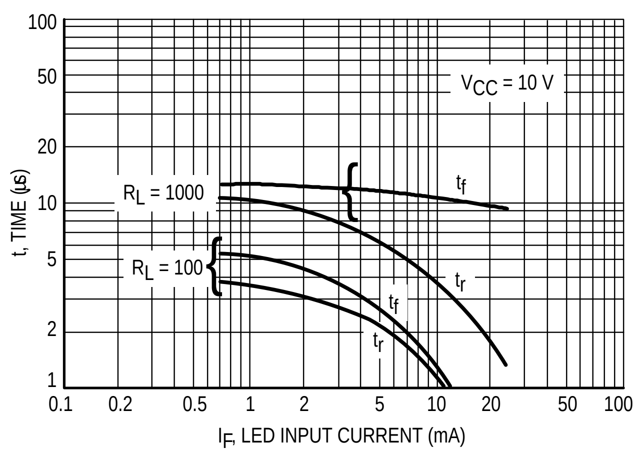


Figure 6. Rise and Fall Times (Typical Values)

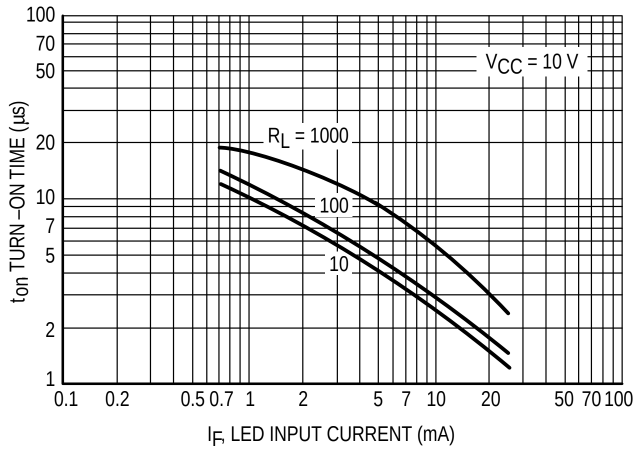


Figure 7. Turn–On Switching Times (Typical Values)

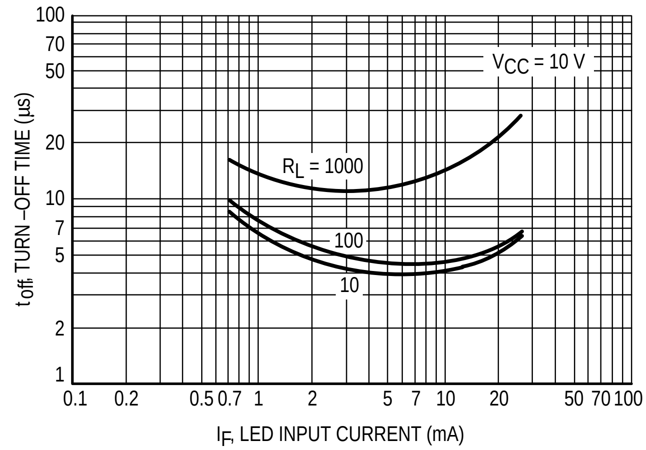


Figure 8. Turn–Off Switching Times (Typical Values)

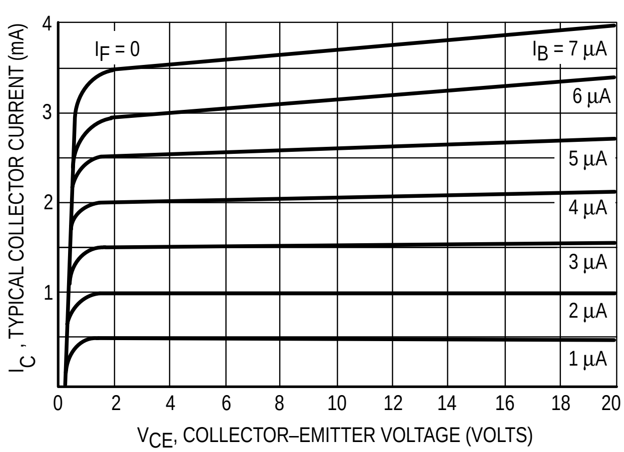


Figure 9. DC Current Gain (Detector Only)

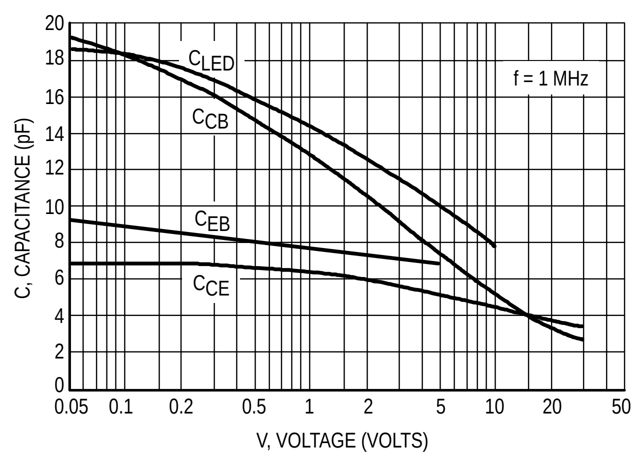


Figure 10. Capacitances versus Voltage

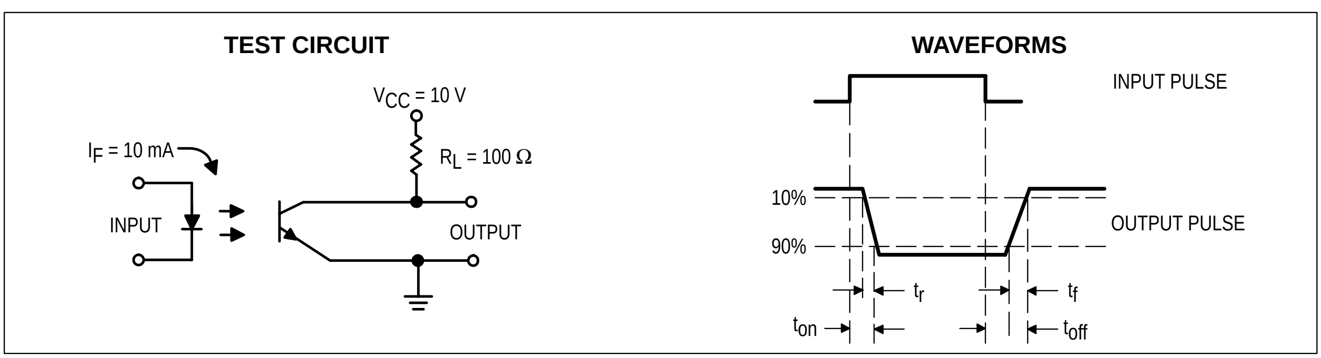
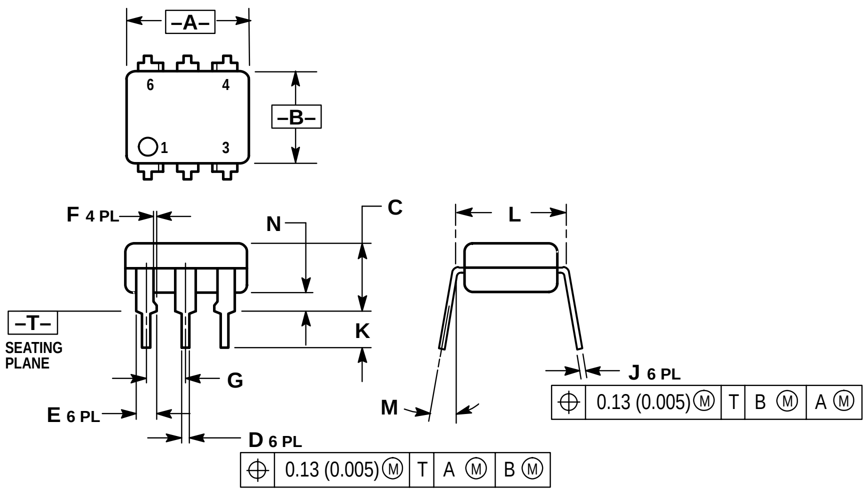


Figure 11. Switching Time Test Circuit and Waveforms

PACKAGE DIMENSIONS

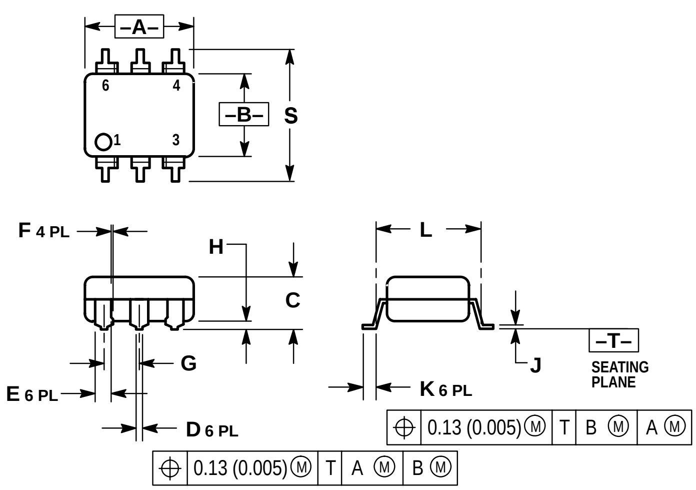


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.320	0.350	8.13	8.89
B	0.240	0.260	6.10	6.60
C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100 BSC		2.54 BSC	
J	0.008	0.012	0.21	0.30
K	0.100	0.150	2.54	3.81
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.015	0.100	0.38	2.54

STYLE 1:
PIN 1. ANODE
2. CATHODE
3. NC
4. EMITTER
5. COLLECTOR
6. BASE

THRU HOLE



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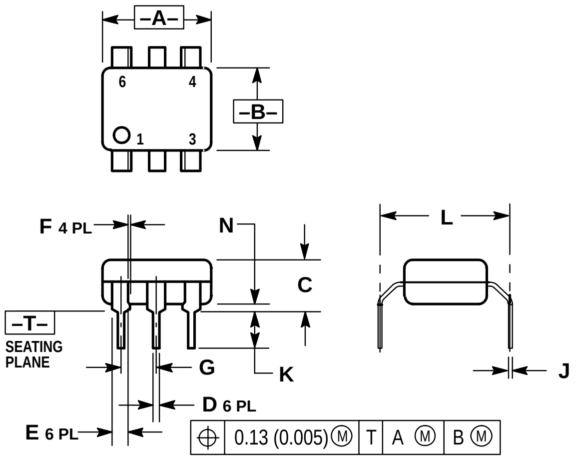
C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100 BSC		2.54 BSC	
H	0.020	0.025	0.51	0.63
J	0.008	0.012	0.20	0.30
K	0.006	0.035	0.16	0.88
L	0.320 BSC		8.13 BSC	
S	0.332	0.390	8.43	9.90

SURFACE MOUNT



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C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100 BSC		2.54 BSC	
J	0.008	0.012	0.21	0.30
K	0.100	0.150	2.54	3.81
L	0.400	0.425	10.16	10.80
N	0.015	0.040	0.38	1.02

0.4" LEAD SPACING

FAIRCHILD SEMICONDUCTOR™

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.